



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-11-15
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement		
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>
		Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	S0M5*XV72BAT	A	3068	2018-11-15
Amount	UoM	Unit type	ST ECOPACK Grade	
150.00	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	3.9-4.9-1.55	16	gull wing	
Comment	Package: POWERSO 16 LEADS EP DIP DOWNSET - MDF for VND7E040AJTR and VND7E040AJ			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015			
Query			Response
1 - Product(s) meets EU RoHS requirement without any exemptions			FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)			FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)			TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions			FALSE
Exemption Id.	Description		
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)		

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017			
Query			Response
1 - Product(s) meets EU ELV requirements without any exemptions			FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)			TRUE
Exemption Id.	Description		
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)		

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.03	Die	167
Lead	3.73	Soft solder	24833

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	3.73	Soft solder	24833
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	3.73	Soft solder	954883

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	S0M5*JV72BAT					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.876	mg	supplier	die	Silicon (Si)	7440-21-3		1.674	mg	892324	11160
				supplier	metallization	Aluminium (Al)	7429-90-5		0.081	mg	43177	540
				supplier	metallization	Copper (Cu)	7440-50-8		0.029	mg	15458	193
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	3200	42
				supplier	Passivation	Silicon Oxide	7631-86-9		0.047	mg	25053	313
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	1066	13
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.025	mg	13326	167
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.002	mg	1066	13
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.010	mg	5330	67
				Leadframe	M-004 Copper and its alloys	70.072	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.069	mg	985	460
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.021	mg	300	140
supplier	metallization	Silver (Ag)	7440-22-4						0.731	mg	10432	4873
supplier	metallization	Lead (Pb)	7439-92-1					7a-Lead in high mel	3.725	mg	954883	24833
Soft solder	Solder	3.901	mg	JIG - R	solder	Silver (Ag)	7440-22-4		0.098	mg	25122	653
				supplier	solder	Tin (Sn)	7440-31-5		0.078	mg	19995	520
				supplier	wire	Copper (Cu)	7440-50-8		0.395	mg	1000000	2633
Bonding wires	M-004 Copper and its alloys	0.395	mg	supplier	wire	Copper (Cu)	7440-50-8		0.395	mg	1000000	2633
				supplier	mold compound	Silica, vitreous	60676-86-0		62.605	mg	864006	417367
				supplier	mold compound	Epoxy Resin	25068-38-6		5.435	mg	75008	36233
				supplier	mold compound	Phenol Resin	29690-82-2		3.623	mg	50000	24153
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		0.362	mg	4996	2413
Encapsulation	M-011 Other inorganic materials	72.459	mg	supplier	mold compound	Quartz	14808-60-7		0.217	mg	2995	1447
				supplier	mold compound	Carbon black	1333-86-4		0.217	mg	2995	1447
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.297	mg	1000000	8647
Connections coating	Solder	1.297	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.297	mg	1000000	8647